

/ Descriptions

TO-92 NPN Silicon NPN transistor in a TO-92 Plastic Package.

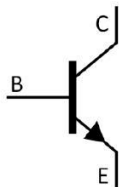
/ Features

$G_{pe}=29\text{dB}$ () ($f=10.7\text{MHz}$)

High power Gain: $G_{pe}=29\text{dB(Typ.)}$ ($f=10.7\text{MHz}$).

/ Applications

High frequency amplifier applications.

/ Equivalent Circuit**/ Pinning**

PIN1 Base PIN 2 Collector PIN 3 Emitter

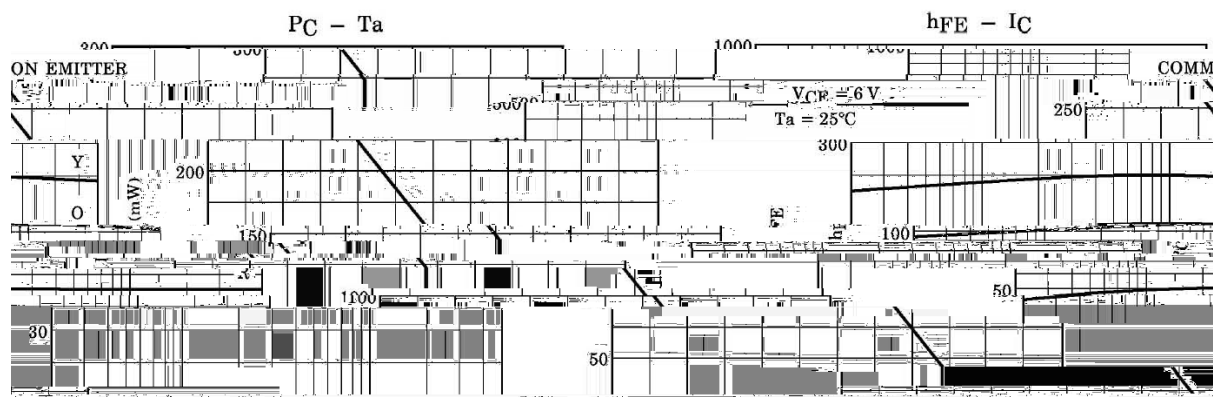
/ hFE Classifications & Marking

h _{FE} Classifications Symbol	R	O	Y
h _{FE} Range	40~80	70~140	120~240

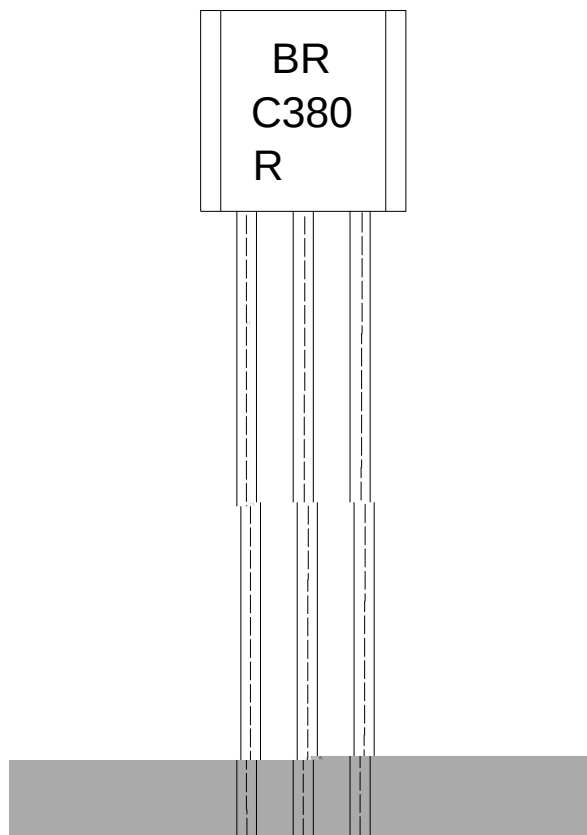
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	35	V
Collector to Emitter Voltage	V_{CEO}	30	V
Emitter to Base Voltage	V_{EBO}	4.0	V
Collector Current - Continuous	I_C	50	mA
Emitter Current - Continuous	I_E	-50	mA
Collector Power Dissipation	P_C	300	mW
Junction Temperature	T_J	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=35V$ $I_E=0$			0.1	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=4.0V$ $I_C=0$			0.1	μA
DC Current Gain	h_E					

/ Electrical Characteristic Curve



/ Marking Instructions



BR:

C380

R: h_{FE}

Note:

BR: Company Code.

C380: Product Type.

R: h_{FE} Classifications Symbol

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;
- 2

255±5

5±0.5sec;
- 3

2 10

/sec.
- 1.Preheating:25~150

,

Time:60~90sec.
- 2.Peak Temp.:255±5

,

Duration:5±0.5sec.
3. Cooling Speed: 2~10

,

/sec.

/ Resistance to Soldering Heat Test Conditions

270±5

10±1 sec.

Temp:270±5

Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	只袋	袋盒	只盒	盒箱	只箱	袋	盒	箱

/ AMMO

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)	
	只纸带	纸带盒	纸带层盒	盒箱	只箱	盒	箱
							小箱 , 大箱

/ Notices